











- MIL-STD 810 Thermal, shock, vibration, Humidity / EMI / EMC
- IP66 Chassis with D38999 connectors
- Intel® 11th Gen. Tiger Lake (H) Xeon® W-11865MLE processor
- Up to 96 GB DDR4 SO-DIMM, non-ECC and ECC
- NVIDIA RTX™ A1000, 2048 CUDA cores, 4GB GDDR6 memory
- MIL-STD-461 18V~36V DC-Input (Options for MIL-704/1275)
- Extreme Temperature : -40°C ~+55 °C
- Optional with External GPU Turbo Kit
- Dimensions: 250(W) x 325 (L) x 100 (H) mm

Special Request:

- Frame Grabber: 4xCH HD-SDI
- Discrete IO: 4xDI 4Xdo
- Dual Redundant MIL-STD-1553 connections
- Dual ARINC 429 input connections

Specifications

SYSTEM

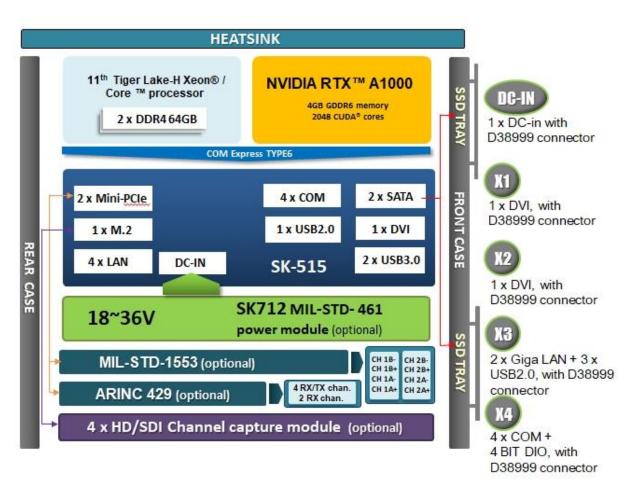
CPU	Intel Xeon W-11865MLE (8Cores/16Threads, 24M Cache, up to 4.50 GHz, 25W)		
Memory type	4 x 260 Pin DDR4 2400MHz SO-DIMM (up to 128GB, XEON®SKU support ECC)		
CHIPSET	CM246		
GPU (optional)	NVIDIA RTX™ A1000 embedded graphics		
	- Standard MXM 3.1 Type A (82 x 70 mm)		
	- 2048 CUDA® cores, 16 RT Cores, and 64 Tensor Cores		
	- 6.66TFLOPS peak FP32 performance		
	- 4GB GDDR6 memory, 128-bit		
On Board Storage	mSATA 512GB		
	1 x M.2(M-key,Type: 2280 , SATA/PCIe 3.0 x 4 NVMe)		
Expansion Slot	2 x Mini PCle Full size (USB / PCle and 1 x micro SIM Card)		
	1 x PCle/104, 1 x FPE		
TPM	TPM 2.0 (SLB9665)		
VIDEO INPUT	4 Channel capture module for 4 x SMA male connectors (optional)		
(optional)			
STORAGE			
SATA	2 x 2.5" SSD		
M.2	1 x M.2(M-key,Type: 2280 , SATA/PCIe 3.0 x 4 NVMe)		
ETHERNET			
Ethernet (Internal)	2 x 10/100/1000 Ethernet Ports		
FRONT I/O			
DC-in	1 x DC-in , with D38999 connector		
X1	1 x DVI , with D38999 connector		
X2	1 x DVI , with D38999 connector		
Х3	2 x GLAN + 3 x USB 2.0, with D38999 connector		
X4	4 x RS232/422/485 + 4 BIT DIO, with D38999 connector		
LED	1 x SSD/HDD LED indicator		
switch	1 x IP65 power button , with LED indicator		
Power	·		
Power input	MIL-STD -461 18V~36V DC-Input		
OPERATING SY	<u> </u>		
OS	Windows® 10 64-bit / Linux (support by request)		
	Wildows To on bit / Elliax (support by request)		

PHYSICAL	
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Dimension	246(W) x 325 (L) x 100 (H)mm		
Weight	(TBD)		
Chassis	SECC		
Heatsink	Heatsink Aluminum Alloy, Corrosion Resistant		
ENVIRONMENTAL	L		
Green Product	RoHS, WEEE compliance		
Operating Temp.	-40°C to +60°C		
Storage Temp.	-40°C to +85°C		
Relative Humidity	5% to 95%, non-condensing		
MIL-STD-810	SPECIFICATIONS (OPE	RATING)	
Method 502.5	Laurana	-20°C, 4 hours, ±3°C	
Procedure 2	 Low Temperature 		
Method 501.5		+55°C, 4 hours, ±3°C	
Procedure 2	 High Temperature 		
Method 507.5	Humidity	85%-95% RH without condensation,	
		24 hours/ cycle, conduct 10 cycles.	
Method 514.6	Vibration	5-500Hz, Vertical 2.20Grms, 40mins x 3axis.	
Method 516.6	Shock	20 Grms, 11ms, 3 axes.	
MIL-STD-810	SPECIFICATIONS (NON	NE-OPERATING)	
Method 502.5	Low Temperature Storage	-33°C, 4 hours, change rate:≦20°C/ Hour	
Procedure 1		-15°C, 72hours (By request)	
Method 501.5	High Temperature	+71°C, 4 hours, change rate:≦20°C/ Hour.	
Procedure 1	Storage	+63°C, 240 hours (By request)	
Method 514.6	Vibration	5-500Hz, Vertical 2.20Grms, 40mins x 3axis.	
Method 516.6	Shock	20 Grms, 11ms, 3 axes.	
MIL-STD-461			
Conducted Emissions	CE102 basic curve	10kHz – 30MHz	
Power Leads			
Radiated	RS103	1.5 MHz – 3GHz, 50 V/m equal for all frequencies	
Susceptibility		2MHz – 80MHz, 50 V/m equal for all frequencies	
Electric Field			
Electric Field		80MHz – 3GHz, 50 V/m equal for all frequencies	
Electric Field		80MHz – 3GHz, 50 V/m equal for all frequencies 3GHz – 5GHz, 50 V/m equal for all frequencies	

Discharge		
Electromagnetic compatibility	EN61000-4-4	Signal and DC Net: 1 kV
Electromagnetic compatibility	EN61000-4-5	Lead vs. ground potential 1Kv, ignal und DC Net: 1 kV
Radio disturbance	EN55022	Class A
Electromagnetic compatibility	EN61000-4-3	10V/m
Electromagnetic compatibility	EN 61000-4-5	Lead vs. ground potential 1Kv, ignal und DC Net: 0.5 kV
MIL-STD-127	5 (OPTIONS)	
Steady State	20V-33V	
Surge Low	18V/500ms	
Surge High	100V/500ms	

Block Diagram



Appearance

